

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Larry Hillyer et al.

Serial No.: Not Yet Assigned

Group Art Unit: Not Yet Assigned

Filed: Concurrently Herewith

Examiner: Not Yet Assigned

For: METHOD AND MATERIAL
FOR REMOVING ETCH
RESIDUE FROM HIGH
ASPECT RATIO CONTACT
SURFACES

Assistant Commissioner for Patents
Washington, D.C. 20231

**POWER OF ATTORNEY BY ASSIGNEE AND
CERTIFICATE BY ASSIGNEE UNDER 37 CFR § 3.73(b)**

Micron Technology, Inc., Assignee of the entire right, title and interest in the above-identified application by virtue of the Assignment attached hereto, hereby appoints the attorneys and agents of the firm of Dickstein Shapiro Morin & Oshinsky LLP, located at 2101 L Street NW, Washington, D.C. 20037, listed as follows: Gary M. Hoffman, 26,411; Thomas J. D'Amico, 28,371; Donald A. Gregory, 28,954; James W. Brady Jr., 32,115; Jon D. Grossman, 32,699; Mark J. Thronson, 33,082; Jeremy A. Cubert, 40,399; Laurence E. Fisher, 37,131; Brian A. Lemm, 43,748; John F. Levis, 34,210; Gianni Minutoli, 41,198; Edwin Oh, P-45,319; Eric Oliver, 35,307; William E. Powell III, 39,803; Paul L. Ratcliffe, 45,290; Mark E. Strickland, 45,138 and Salvatore P. Tamburo, P-45,153, and also attorneys of Micron Technology, Inc. as its attorneys with full power of

substitution to prosecute this application and to transact all business in the Patent and Trademark Office in connection therewith.

The Assignee certifies that the above-identified assignment has been reviewed and to the best of the Assignee's knowledge and belief, title is in the assignee.

Please direct all correspondence regarding this application to the following:

Dickstein Shapiro Morin & Oshinsky LLP
2101 L Street NW
Telephone: (202) 785-9700
Fax: (202) 887-0689

MICRON TECHNOLOGY,



Michael L. Lynch
Chief Patent Counsel
Registration No. 30,871

Dated: Oct 11, 2000

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**METHOD AND MATERIAL FOR REMOVING ETCH RESIDUE
FROM HIGH ASPECT RATIO CONTACT SURFACES**

The specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by an amendment, if any, specifically referred to in this oath or declaration.

I acknowledge the duty to disclose all information known to me which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code § 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

NONE

I hereby claim the benefit under Title 35, United States Code, § 120/365 of any United States and PCT international application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56(a) which became available between the filing date of the prior application and the national or PCT international filing date of this application:

NONE

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Please address all correspondence to Thomas J. D'Amico of Dickstein Shapiro Morin & Oshinsky LLP located at 2101 L Street NW

Washington, DC 20037-1526. Telephone calls should be made to (202) 785-9700.

Full name of first inventor: Larry Hillyer

Inventor's signature: Larry Hillyer Date: 8/31/00

Residence: Boise, Idaho

Citizenship: United States of America

Post Office Address: 1856 Danmore Dr.
Boise, ID 83712

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
DECLARATION FOR PATENT APPLICATION

Signature Page for Second Inventor

Full name of second inventor: Steve Byrne

Inventor's signature:

Steve Byrne

Date: 8-31-00

Residence: Boise, Idaho

Citizenship: United States of America

Post Office Address: #6 Mule Deer Place
Boise, ID 83716

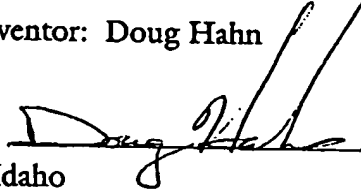
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DECLARATION FOR PATENT APPLICATION

Signature Page for Fourth Inventor

Full name of fourth inventor: Doug Hahn

Inventor's signature:



Date:

8/31/00

Residence: Boise, Idaho

Citizenship: United States of America

Post Office Address: 6828 Fairfield Avenue
Boise, ID 83709

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DECLARATION FOR PATENT APPLICATION

Signature Page for Third Inventor

Full name of third inventor: Kelly Williamson

Inventor's signature: Kelly Williamson Date: 8/31/00

Residence: Boise, Idaho

Citizenship: United States of America

Post Office Address: 941 Ironside Drive
Boise, ID 83706